Thermal Management Technologies (Heat Sinks): Market Research Report

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Abstracts

This report analyzes the worldwide markets for Thermal Management Technologies (Heat Sinks) in Millions of US$.

The report on ‘Thermal Management Technologies (Heat Sinks)’ analyzes the Heat Sinks market by the following product segments: Metal Extruded Heat Sinks, Stamped Heat Sinks, Bonded or Fabricated Fin Heat Sinks, and Folded Fin Heat Sinks.

The report provides separate comprehensive analytics for the US, Canada, Japan, Europe, Asia-Pacific, and Rest of World.

Annual forecasts are provided for each region for the period of 2006 through 2015.

The report profiles 180 companies including many key and niche players worldwide such as Aavid Thermalloy, LLC, Aerocool Advanced Technologies Corp., ADDA Corp., Advanced Thermal Solutions, Inc., Ajigo Corp., Akasa Group, Alpha Company Ltd., Asia Vital Components Co.Ltd., ASUSTeK Computer Inc., Chaun Choung Technology Corp., Cooler Master Co.Ltd., Dynatron Corp., Enertron Inc., GlacialTech, Inc.. JMC Products, Inc., Melcor Corp., Neng Tyi Co.Ltd., Polo Tech Co.Ltd., R-Theta Thermal Solutions, Inc., Radian Heat Sinks, Sumitomo Electric Industries, Ltd., Swiftech, Taisol Electronics Co.Ltd., TennMax United, Thermal Integration Technology, Inc., Thermacore, Thermalright, Inc., Thermaltake Technology Co., Ltd., Titan Computer Co.Ltd., Verax Ventilatoren GmbH, Vette Corp., and Wakefield Thermal Solutions, Inc.

Market data and analytics are derived from primary and secondary research.

Company profiles are mostly extracted from URL research and reported select online

sources.

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Akasa Group (UK)
Alpha Company Ltd. (Japan)
Asia Vital Components Co. Ltd. (Taiwan)
ASUSTeK Computer Inc. (Taiwan)
Chaun Choung Technology Corp. (Taiwan)
Cooler Master Co. Ltd. (Taiwan)
Dynatron Corp. (USA)
Enertron Inc. (USA)
GlacialTech, Inc. (Taiwan)
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Melcor Corp. (USA)
Neng Tyi Co. Ltd (Taiwan)
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R-Theta Thermal Solutions, Inc. (Canada)
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Sumitomo Electric Industries, Ltd. (Japan)
Swiftech (US)
Taisol Electronics Co. Ltd. (China)
TennMax United (USA)
Thermal Integration Technology, Inc (Taiwan)
Thermacore (USA)
Thermalright, Inc. (USA)

Thermaltake Technology Co., Ltd (Taiwan)
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Enertron, Inc. (USA)
JMC Products, Inc. (USA)
Melcor Corp. (USA)
Radian Heat sinks (US)
Swiftech (US)
Tennmax United (USA)
Thermacore (USA)
Thermalright, Inc. (USA)
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ASUSTeK Computer, Inc. (Taiwan)
Chaun Choung Technology Corp. (Taiwan)
Cooler Master Co. Ltd. (Taiwan)
EVERCOOL Thermal Co., Ltd. (Taiwan)
GlacialTech, Inc. (Taiwan)
Kuang Thousand Technology Co., Ltd. (Taiwan)
Neng Tyi Co. Ltd (Taiwan)
Polo Tech Co. Ltd (Taiwan)
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Total Companies Profiled: 180 (including Divisions/Subsidiaries - 207)
Region/CountryPlayers
The United States
Canada
Japan
Europe
France
Germany
The United Kingdom
Italy
Spain
Rest of Europe
Asia-Pacific (Excluding Japan)

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